

Wirebond optical module machine



Overview

Wirebond AOI Machine - Wafer Automated Optical Inspection (AOI) Equipment from TT Vision Holdings Berhad. Get product specifications, Download the Datasheet, Request a Quote and get pricing for Wirebond AOI Machine on Semiconductor DirectorySuperior performance ideal for wirebond applications. Improve yields, processes and productivity and reduce costly returns from the field. The system is particularly easy to configure. Photonic wire bonding (PWB) utilises advanced three-dimensional (3D) nano-printing to manufacture single-mode freeform waveguides. Enabling photonic integration between coarsely pre-positioned optical elements and ensuring highly efficient coupling between waveguides of vastly different mode field. Vega is a High Precision Wire bond Inspection (AOI) solution equipped with the latest & high-specification 3D technologies which able to perform a smarter and high accuracy height measurement inspection on the die and on wirebond. It's designed to support inspection before and after the. An advanced automated wire bond inspection system that integrates high resolution camera and latest technology of optics and illumination.



Article Content

Sep 18, 2025

Wirebonding

Wirebonding is a commonly used method for creating interconnections between an IC on a silicon die and its packaging, in which a thin wire is connected from a bond pad on the device to a

Feb 12, 2026

Drahtbonden

Bondbemusterungen (Qualifizierung von Oberflächen bezüglich der Bondbarkeit), Aufbau von Prototypen, Kleinstserienfertigung, Machbarkeitsstudien,

Mar 20, 2026

3 Bonding Equipment

This conventional approach has been used for a long time in wirebond machine development, but as we go to higher precision in fine pitch bonding, the spindle concept has limitations.

Jun 04, 2026

Photonic integration and packaging with Photonic Wire

With both PWB and facet-attached micro-optical elements in their technology portfolio, Vanguard Automation's mission is to advance photonic packaging and

Oct 09, 2025

3D Wire Bond Inspection

3D Measurement for Even Greater Inspection Reliability As the market leader in wire bond inspection, Viscom offers accurate measurement of heights for both thick and thin wires. The automated

Apr 08, 2026

Wire Bond Electrical Structural Test Methodologies

Wire bonding, a foundational process in microelectronics, is essential for establishing a robust and low-resistance electrical connection between semiconductor chips

Mar 11, 2026

iS6059 Wire Bond Inspection – Viscom

With the iS6059 Wire Bond Inspection system, Viscom offers the best inline technology and top performance for the automatic optical inspection of wire

Nov 04, 2025

Advancements in Inspection Technologies:

One of the critical areas of focus has been on Wirebond AOI (Automated Optical Inspection), where traditional methods often struggled to effectively scrutinize

Nov 26, 2025

Bonding Wire

The bonding machine uses a capillary through which the bond wire is threaded. An electrical spark (1) is used to form the "ball" (2) at the end of the bond wire. The ball is pressed to the bond pad (3) under

May 25, 2026

3D Wire Bond AOI – IDEAL VISION INTEGRATION

Product Details Zeta Series ADVANCED 3D WIREBOND AOI MACHINE An advanced automated wire bond inspection system that integrates high resolution

Sep 27, 2025

Vega Wirebond AOI Inspection | 3D Wire Bond Inspection

Vega is a High Precision Wire bond Inspection (AOI) solution equipped with the latest & high-specification 3D technologies which able to perform a smarter and

Jun 01, 2026

Wirebond AOI Machine

The Wirebond AOI Machine incorporates state-of-the-art 3D profiling technology, enabling detailed and accurate inspection of wirebond, die, and epoxy features for enhanced defect detection.

Nov 01, 2025

Bond Inspection – Viscom

Automatic inline inspection of thin and thick wire connections allows quick and reliable detection of defects on wires with complex reflectivity characteristics.

Jan 01, 2026

Nordson Optical Inspection SQ3000M2 Wirebond Inspection

Improve yields, processes and productivity and reduce costly returns from the field. This high-speed, inline automated optical inspection and metrology system is ideal for wire bond

Aug 05, 2025

Wire Bond Inspection for the Electronic Device Industry

Optical zoom in the VS Series captures detailed images with a single click, improving wire bond defect detection. It is perfect for small components and ensures minor defects are accurately identified and

Jul 20, 2025

Vanguard Automation | Photonic Wire Bonds

Delivering the complete solution for photonic integration with modular machines, software and dedicated materials. Over twenty years of expertise in research and industrial automation.

Apr 02, 2026

VEGA SERIES High Precision 3D Wirebond AOI Solution

VEGA SERIES High Precision 3D Wirebond AOI Solution SECURE EVERY BOND, EVERY TIME Vega Series – secure every single wire bond with our high

Jan 20, 2026

SQ3000 M2

Superior performance ideal for wirebond applications. SQ3000M2 automated optical inspection (AOI) ensures product quality is maximized. Improve yields, processes and productivity and reduce costly

Jun 14, 2026

Application Of Gold Wire Ball Bonding In Optical Module

It offers superior signal integrity and has gradually become one of the mainstream packaging processes for high-speed optical modules. Besides

Sep 16, 2025

New Technologies and New Applications for Wire Bonding

New Technologies and New Applications for Wire Bonding We have in the previous chapters discussed the issues related to design, materials, equipment, quality and reliability issues of gold wire bonding

Jun 17, 2026

Innovations in Wire Bond Inspection

Other process deviations which can be detected include variations in bond position following the changing of a bond tool, optical changes in wedges caused by bond tool wear, and variations in loop

Sep 10, 2025

Wirebond AOI Machine

The Wirebond AOI Machine stands as a cutting-edge solution for inspecting critical components in semiconductor manufacturing, offering advanced features for defect detection and precise parameter

Nov 19, 2025

Advanced Wire Bonding Technology: Materials, Methods, and Testing

nent handlers, automatic bonding machines can sustain such rates for hours. Such automation, with its concomitant accuracy and improved process control has dropped wirebond failure rates for

Nov 23, 2025

Automatic Optical Inspection System

High Speed stroboscopic 2D vision inspection system for die attached and wirebond quality in back-end semiconductor processes. User friendly HMI for easy recipe creation and management.

Dec 10, 2025

Wire Bonding Inspection

Summary Digital optical microscopy by Smartzoom 5 is shown as a viable technique in wire bonding inspection. Smartzoom 5 digital microscope is a highly repeatable and connected optical inspection

Feb 27, 2026

3D Wire Bond AOI – IDEAL VISION INTEGRATION

An advanced automated wire bond inspection system that integrates high resolution camera and latest technology of optics and illumination. With configurable

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Wirebond AOI Machine

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Jan 17, 2026

Advanced Wire Bonding Technology: Materials,

Using automatic component handlers, automatic bonding machines can sustain such rates for hours. Such automation, with its concomitant accuracy and improved

May 29, 2026

iS6059 Wire Bond Inspection

With the iS6059 Wire Bond Inspection system, Viscom offers the best inline technology and top performance for the automatic optical in-spection of wire bonds. Where high throughput is a must,

Contact Us

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